

OUR LEADERSHIP TECHNOLOGY



Industry-Leading IP

Executing leadership CPU, GPU, DPU, FPGA and Adaptive SOC products and roadmaps



Advanced Technology

Driving leadership process technology and 3D chiplet packaging



Data Center Leadership

Delivering innovation in cloud, enterprise, AI and accelerated computing

Software Enablement

Open-source software co-designed with hardware and optimized for performance across heterogenous solutions

OUR LEADERSHIP PRODUCTS



Data Center

Leadership data center solutions with server CPUs, GPUs, FPGAs, DPUs, SmartNICs and adaptive SOCs



Client

Leadership CPUs and APUs for notebook and desktop PCs and commercial workstations





Gaming

Top-to-bottom desktop and notebook GPUs, game console and semi-custom SOCs

Embedded

Leadership FPGAs, adaptive SOCs and SOMs, and embedded CPUs and GPUs for a broad set of markets

Opportunity: National Semiconductor Technology Center and National Advanced Packaging Manufacturing Program

AMD Program Recommendations:

- Independent Legal Entity: Public/private partnership established by end of 2023
- Aligned Governance of NSTC and NAPMP: Secretary of Commerce should create a BOD to oversee both the NSTC and NAPMP to ensure synergy and alignment of investments.
- **Geographic Diversity for Infrastructure investments:** Protoyping capabilities should be built in a geographically distributed model encompassing up to six (6) coalitions of excellence (COEs) aligned around major technical thrusts:
 - Memory COE
 - Logic COE
 - Mixed-Signal, RF, and Power COE
 - Architecture, Design, and tools COE
 - Life Science COE
 - NAPMP Packaging COE
- Identify a set of nationwide grand challenges
 - These grand challenges should span three (3) complementary areas that would benefit from large-scale nationwide collaboration: advanced computing into the zettascale era; significantly reducing design complexity; and proliferating semiconductors in life sciences applications.

Opportunity: Microelectronics Workforce Development Fund

AMD Program Recommendations:

- National Microelectronics Education and Training Network: Establish by end of 2023
- Upgrade laboratory facilities and equipment: At least 50 "hub" universities geographically distributed across the country including MSIs
- **Update curriculum development:** Widely distribute across national network of universities and community colleges
- **Hire:** Recruit at least 100 new microelectronics faculty
- Support university access to industry-standard resources: electronic design automation (EDA) and technology computer aided design (TCAD) software tools, design flows, and multi-project wafer (MPW) fabrication runs in semiconcutor foundries for teaching and research purposes
- Industry dynamics: While manufacturing jobs are important, design jobs are experiencing exponential growth

#